Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BG 3130R H6327	**Issued**	29. August 2013
MA#	MA000845500		
Package	PG-SOT363-6-4	**Weight***	6.27 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.005	0.08		816	
	non noble metal	tin	7440-31-5	0.001	0.02		210	
	inorganic material	silicon	7440-21-3	0.045	0.71	0.81	7113	8139
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		92	
	non noble metal	titanium	7440-32-6	0.003	0.05		458	
	non noble metal	chromium	7440-47-3	0.009	0.14		1374	
	non noble metal	copper	7440-50-8	2.860	45.61	45.81	456053	457977
wire	non noble metal	copper	7440-50-8	0.015	0.23	0.23	2336	2336
encapsulation	organic material	carbon black	1333-86-4	0.031	0.49		4880	
	plastics	epoxy resin	-	0.658	10.49		104920	
	inorganic material	silicondioxide	60676-86-0	2.372	37.82	48.80	378201	488001
leadfinish	non noble metal	tin	7440-31-5	0.213	3.40	3.40	34002	34002
plating	noble metal	silver	7440-22-4	0.060	0.95	0.95	9545	9545
*deviation	< 10%				Sum in total:	100,00		1000000

Important Remarks:

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